Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info	Subsectionals *	A-D
	Manufacturing Info		*** : Required Field**

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-05-16
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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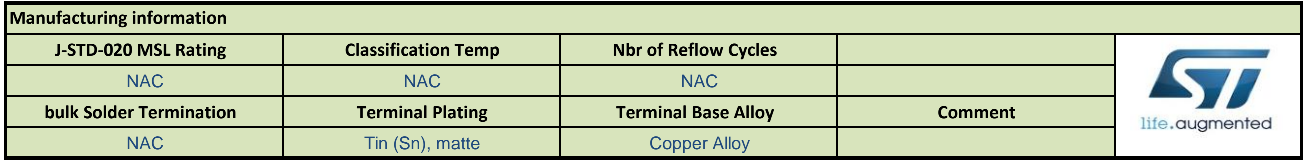
Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
STIPN2M50T-HL	IIFA*UG52B6F	A	Z8GA	2016-05-16
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	3730.00	mg	Each	ECOPACK® 2



Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		life.augmented
NAC	NAC	NAC		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
ZIP	29.05 -12.35 - 3	26	Through-hole	
Comment	Package: NDIP-26L			

QueryList : ROHS directive 2011/65/EU _ July 2011		
Query		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		**true**
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
5 - Product(s) is obsolete, no information is available		false
6 - Product(s) is unknown, no information is available		false
Exemption Id.	**Description**	
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)	
7c-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound	

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						**Mfr Item Name**	**IIFA*UG52B6F**					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Dies	Other inorganic materials	38.071	mg	supplier	die	Silicon (Si)	7440-21-3		36.876	mg	968611	9886
				supplier	metallization	Aluminium (Al)	7429-90-5		0.504	mg	13238	135
				supplier	Passivation	Silicon Nitride	12033-89-5		0.240	mg	6304	64
				supplier	Passivation	Silicon Oxide	7631-86-9		0.366	mg	9614	98
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.003	mg	78	1
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.002	mg	53	1
				supplier	back side metallization	Gold (Au)	7440-57-5		0.006	mg	158	2
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.060	mg	1576	16
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.014	mg	368	4
NTC	Other inorganic materials	4.992	mg	supplier	ceramic	Manganese oxide	1317-35-7		3.190	mg	639022	855
				supplier	ceramic	Nickel oxide	1313-99-1		0.798	mg	159856	214
				supplier	ceramic	Cobalt oxide	1308-06-1		0.704	mg	141026	189
				supplier	ceramic	Gold (Au)	7440-57-5		0.285	mg	57091	76
				JIG - R	metallization	Lead borate Glass	65997-18-4	7c-I-Electrical and e	0.015	mg	3005	4
Leadframe	Copper and its alloy	1014.282	mg	supplier	alloy	Copper(CU)	7440-50-8		984.352	mg	970491	263901
				supplier	alloy	Iron(Fe)	7439-89-6		26.379	mg	26008	7072
				supplier	alloy	Phosphorus(P)	12185-10-3		1.522	mg	1501	408
				supplier	alloy	Zinc(Zn)	7440-66-6		2.029	mg	2000	544
Die attach	Other inorganic materials	1.759	mg	supplier	glue or tape	Epoxyde Bisphenol A Resin	25068-38-6		0.159	mg	90392	43
				supplier	glue or tape	Diaminodiphenylsulfone	80-08-0		0.035	mg	19898	9
				supplier	glue or tape	Ethoxyethoxy-ethyl Acetate	112-15-2		0.386	mg	219443	104
				supplier	glue or tape	Bisphenol A diglycidyl ether polymer	25036-25-3		0.247	mg	140421	66
				supplier	glue or tape	Glycol ether ester	Proprietary		0.035	mg	19898	9
				supplier	glue or tape	Silica, vitreous	60676-86-0		0.536	mg	304719	144
				supplier	glue or tape	Aluminium oxide	1344-28-1		0.352	mg	200114	94
				Supplier	glue or tape	Aminopropyltriethoxysilane	919-30-2		0.009	mg	5115	2
Soft solder	Solder	7.294	mg	JIG-R	soft Solder	Lead (Pb)	7439-92-1	7a-Lead in high me	6.564	mg	899918	1760
				supplier	soft Solder	Tin(Sn)	7440-31-5		0.730	mg	100082	196
Bonding wire	Precious metals	2.377	mg	Supplier	wire	Gold (Au)	7440-57-5		2.377	mg	1000000	637
Encapsulation	Other inorganic materials	2641.121	mg	Supplier	molding compound	Epoxy Resin	25068-38-6		132.056	mg	50000	35404
				Supplier	molding compound	Epoxy Resin 2	Proprietary		132.056	mg	50000	35404
				Supplier	molding compound	Phenol Resin	29690-82-2		132.056	mg	50000	35404
				Supplier	molding compound	Carbon black	1333-86-4		7.922	mg	2999	2124
				Supplier	molding compound	Crystal silica	60676-86-0		1716.730	mg	650001	460249
				Supplier	molding compound	Metal hydroxide	21645-51-2		396.168	mg	150000	106211
				Supplier	molding compound	Amorphous silica	14808-60-7		124.133	mg	47000	33280
Connections coating	Solder	20.104	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		20.104	mg	1000000	5390